

Parker Chomerics CHO-BOND® 592 Conductive Adhesive

Category: Polymer, Adhesive, Thermoset

Material Notes:

Description: CHO-BOND® 500 Series Adhesive/Sealant Compounds; These pure silver-filled materials are used where tight tolerances require thin bond lines. Various cure cycles are available, and the materials are formulated for easy application by caulking gun, spatula, needle spotting, or silk screening. Their use for bonding mesh gaskets, printed circuit board repair, chip bonding, rear window defogger repair, and as low-temperature-activated flexible solders demonstrates their versatility. CHO-BOND® 592 adhesive bonds dissimilar materials effectively. It combines long pot-life and excellent adhesion with low viscosity, a low coefficient of thermal expansion, very low thermal impedance and good thermal shock resistance. The material excels as a sealant for microwave modules and components and is useful for circuit board repair and grounding applications.Information provided by Chomerics

Order this product through the following link:

http://www.lookpolymers.com/polymer_Parker-Chomerics-CHO-BOND-592-Conductive-Adhesive.php

Physical Properties	Metric	English	Comments
Specific Gravity	2.35 - 2.85 g/cc	2.35 - 2.85 g/cc	
Thickness	25.0 microns	0.984 mil	Recommended

Mechanical Properties	Metric	English	Comments
Shear Strength	>= 10.35 MPa	>= 1501 psi	Lap

Thermal Properties	Metric	English	Comments	
Maximum Service Temperature, Air	99.0 °C	210 °F		
Minimum Service Temperature, Air	-62.0 °C	-79.6 °F		

Electrical Properties	Metric	English	Comments
Volume Resistivity	<= 0.050 ohm-cm	<= 0.050 ohm-cm	DC

Metric	English	Comments
30.0 min	0.500 hour	
@Temperature 100 °C	@Temperature 212 °F	
10100 min	168 hour	
@Temperature 24.0 °C	@Temperature 75.2 °F	
9.00 Month	9.00 Month	
	30.0 min @Temperature 100 °C 10100 min @Temperature 24.0 °C	30.0 min 0.500 hour @Temperature 100 °C @Temperature 212 °F 10100 min 168 hour @Temperature 24.0 °C @Temperature 75.2 °F

Descriptive Properties	Value	Comments	
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Descriptive Properties	Value	Comments
Consistency	Nearly liquid	
Coverage	170.3 cm ² /g	
Filler	Ag	
Mix Ratio	100:50	

Contact Songhan Plastic Technology Co.,Ltd.

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